

Material Content Data Sheet Collection

Sales Product Name	IGB08N120S7
MA#	SP005403471
Package	PG-TO263-3-2
Versions	123168,123169
Issued	26. August 2024



Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IGB08N120S7	**Issued**	26. August 2024
MA#	MA005876828		
Package	PG-TO263-3-2	**Weight***	1461.70 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.540	0.174	0.174	1738	1738
leadframe	inorganic material	phosphorus	7723-14-0	0.256	0.018	58.343	175	583432
	non noble metal	iron	7439-89-6	0.853	0.058		583	
	non noble metal	copper	7440-50-8	851.691	58.267		582673	
wire	non noble metal	aluminium	7429-90-5	1.002	0.069	0.069	685	685
encapsulation	inorganic material	zincoxide	1314-13-2	5.932	0.406	40.583	4058	405834
	miscellaneous	miscellaneous	-	23.728	1.623		16233	
	plastics	epoxy resin	-	88.981	6.088		60875	
	inorganic material	silicondioxide	60676-86-0	474.565	32.467		324667	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.661	0.661	6606	6606
plating	inorganic material	phosphorus	7723-14-0	0.001	0.000	0.016	0	157
	non noble metal	nickel	7440-02-0	0.228	0.016		156	
solder	non noble metal	tin	7440-31-5	0.045	0.003	0.155	31	1548
	noble metal	silver	7440-22-4	0.057	0.004		39	
	non noble metal	lead	7439-92-1	2.161	0.148		1479	
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com



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RoHS | Halogen-Free

Sales Product Name	IGB08N120S7	**Issued**	26. August 2024
MA#	MA005876828		
Package	PG-TO263-3-2	**Weight***	1461.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.540	0.174	0.174	1738	1738
leadframe	inorganic material	phosphorus	7723-14-0	0.256	0.018	58.344	175	583436
	non noble metal	iron	7439-89-6	0.853	0.058		583	
	non noble metal	copper	7440-50-8	851.691	58.268		582678	
wire	non noble metal	aluminium	7429-90-5	0.962	0.066	0.066	658	658
encapsulation	inorganic material	zincoxide	1314-13-2	5.932	0.406	40.586	4059	405856
	miscellaneous	miscellaneous	-	23.729	1.623		16234	
	plastics	epoxy resin	-	88.985	6.088		60878	
	inorganic material	silicondioxide	60676-86-0	474.587	32.469		324685	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.661	0.661	6607	6607
plating	inorganic material	phosphorus	7723-14-0	0.001	0.000	0.016	0	157
	non noble metal	nickel	7440-02-0	0.228	0.016		156	
solder	non noble metal	tin	7440-31-5	0.045	0.003	0.155	31	1548
	noble metal	silver	7440-22-4	0.057	0.004		39	
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